

Middle Power LED Series  
2835 1.0W 9V Ra80 Hot bin

# LM283B+

## SL SLM rank



Designed for better lm/\$ (Lamps)

### Features & Benefits

- 0.9W Class mid power LED
- Standard form factor for design flexibility (2.8 × 3.5 × 0.65mm)



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## 1. Characteristics

### a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	T <sub>a</sub>	-40 ~ +80	°C	-
Storage Temperature	T <sub>stg</sub>	-40 ~ +80	°C	-
LED Junction Temperature	T <sub>j</sub>	125	°C	-
Forward Current	I <sub>F</sub>	110	mA	-
Peak Pulsed Forward Current	I <sub>FP</sub>	200	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	2	kV	-

**Note:**

Proper current derating must be observed to maintain junction temperature below the maximum at all time.

**b) Electro-optical Characteristics (I<sub>F</sub> = 100 mA, T<sub>S</sub> = 25 °C)**

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage (VF)	V	SG or SK	GZ	8.8	-	9.1
			G1	9.1	-	9.4
			G2	9.4	-	9.7
Color Rendering Index (Ra)	-	5	G3	9.7		10.0
				80	-	-
				-	15	-
Thermal Resistance (junction to solder point)	°C/W			-	120	-
Beam Angle	°			-		-

**Note:**

Samsung maintains measurement tolerance of: forward voltage = ±0.2 V, CRI = ±3

**b) Electro-optical Characteristics (I<sub>f</sub> = 100 mA, T<sub>s</sub> = 25 °C)**

Item	CRI (R <sub>a</sub> ) Min.	Nominal CCT (K)	Bin	100mA	
				Min.	Max.
Luminous Flux (Φ <sub>v</sub> )	80	2700	SL	105	115
			SM	115	125
		3000	SL	106	116
			SM	116	126
		3500	SL	110	120
			SM	120	130
		4000	SL	115	125
			SM	125	135
		5000	SL	117	127
			SM	127	137
		5700	SL	116	126
			SM	126	136
		6500	SL	115	125
			SM	125	135

**Note:**

Samsung maintains measurement tolerance of: forward voltage = ±0.2V, luminous flux = ±5 %, CRI = ±3



a) Luminous Flux Bins ( $I_F = 100 \text{ mA}$ ,  $T_s = 25^\circ\text{C}$ )

CRI ( $R_a$ )	Nominal CCT (K)	Product Code	Flux Bin	Flux Range ( $\Phi_v$ , lm)
80	2700	SPMWH1229AQ5SGW★SL	SL	105 ~115
		SPMWH1229AQ5SGW★SM	SM	115 ~ 125
	3000	SPMWH1229AQ5SGV★SL	SL	106 ~ 116
		SPMWH1229AQ5SGV★SM	SM	116 ~ 126
	3500	SPMWH1229AQ5SGU★SL	SL	110 ~ 120
		SPMWH1229AQ5SGU★SM	SM	120 ~ 130
	4000	SPMWH1229AQ5SGT★SL	SL	115 ~125
		SPMWH1229AQ5SGT★SM	SM	125 ~135
	5000	SPMWH1229AQ5SGR★SL	SL	117 ~127
		SPMWH1229AQ5SGR★SM	SM	127 ~137
	5700	SPMWH1229AQ5SGQ★SL	SL	116 ~ 126
		SPMWH1229AQ5SGQ★SM	SM	126 ~136
	6500	SPMWH1229AQ5SGP★SL	SL	115 ~125
		SPMWH1229AQ5SGP★SM	SM	125 ~135

**Note:** ★ can be "0" (Whole bin), "M" (Quarter bin) or "K" (Kitting bin) of the color binning

## b) Kitting rule

### 1) Kitting bin Concept

1. Under agreement between customer and SAMSUNG ELECTRONICS, SAMSUNG can supply kitting bin (VF, Color, Im).
2. A forward voltage (VF) of kitting bin is combined by a pair of same VF rank such as (GZ+GZ), (G1+G1), (G2+G2) or (G3+G3).
3. A Chromaticity Coordinates of kitting bin is mixed by kitting procedure.(below kitting simulation)

### [Kitting example]

D	E	F	G
9	A	B	C
5	6	7	8
1	2	3	4

### [Binning Information]

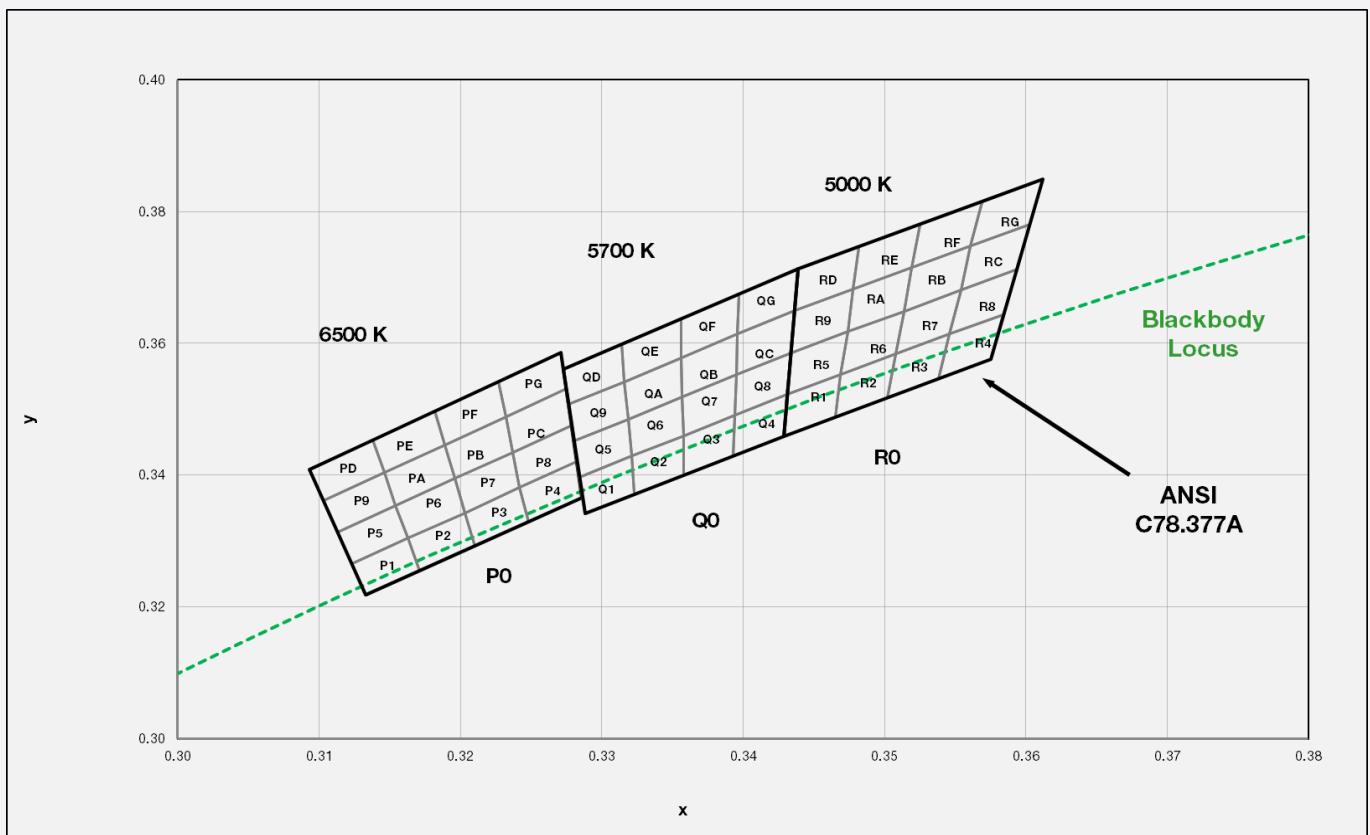
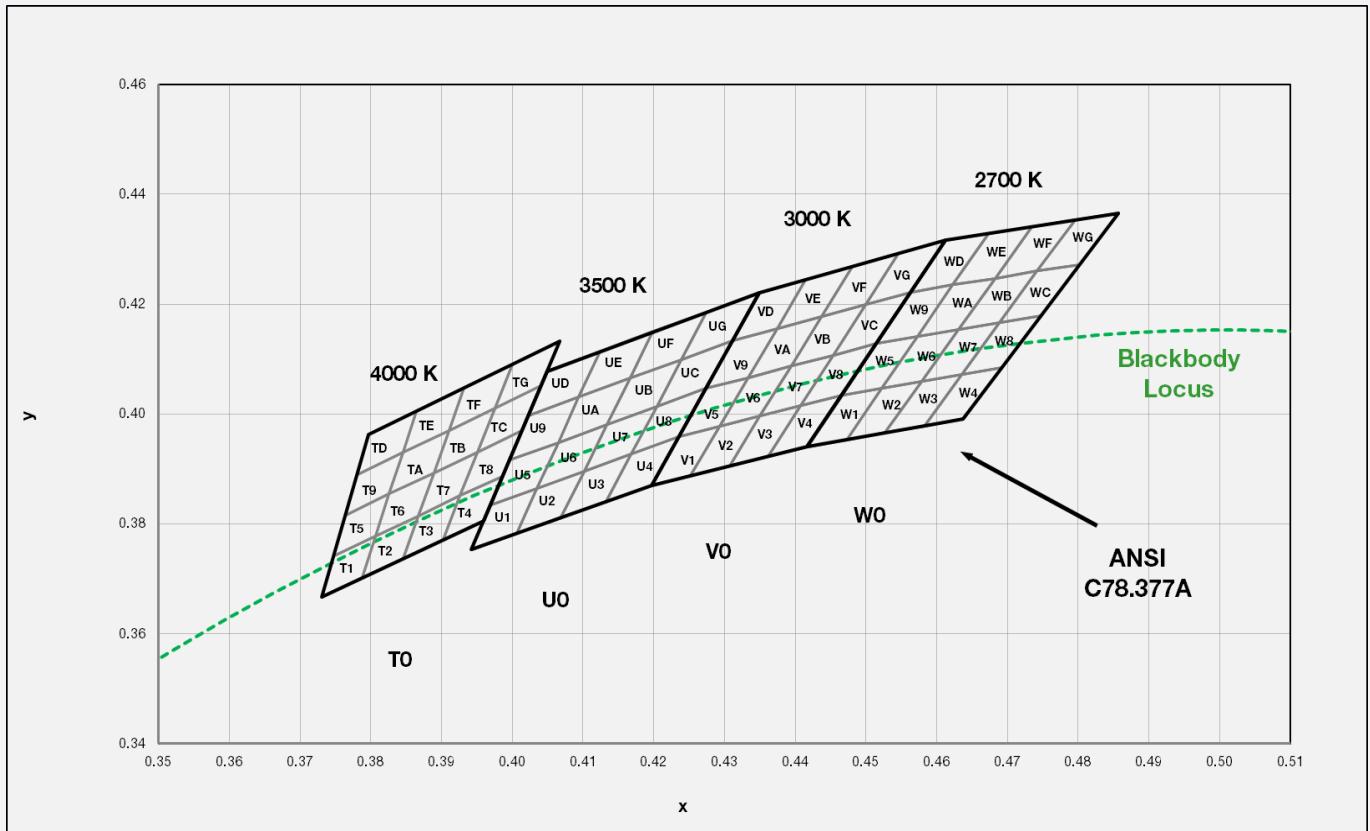
	Bin #1	Bin #2
VF	GZ	GZ
	G1	G1
	G2	G2
	G3	G3
CIE	1, 2, 5 bin	C, F, G bin
	6, 7, A, B bin	6, 7, A, B bin
	3, 4, 8 bin	9, D, E bin



**d) Voltage Bins ( $I_F = 100 \text{ mA}$ ,  $T_s = 25^\circ\text{C}$ )**

CRI ( $R_a$ ) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
-	-	-	GZ		8.8 ~ 9.1
-	-	-	SG	G1	9.1 ~ 9.4
-	-	-	or		
-	-	-	SK	G2	9.4 ~ 9.7
				G3	9.7 ~ 10.0

e) Chromaticity Region & Coordinates ( $I_F = 100 \text{ mA}$ ,  $T_s = 25^\circ\text{C}$ )





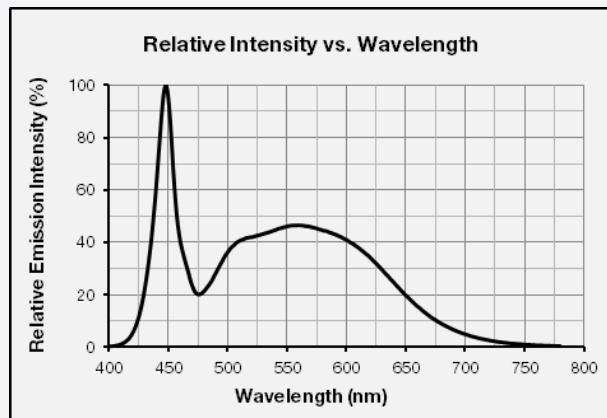




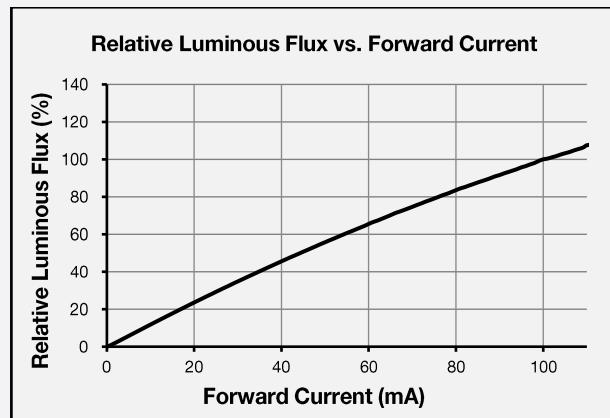
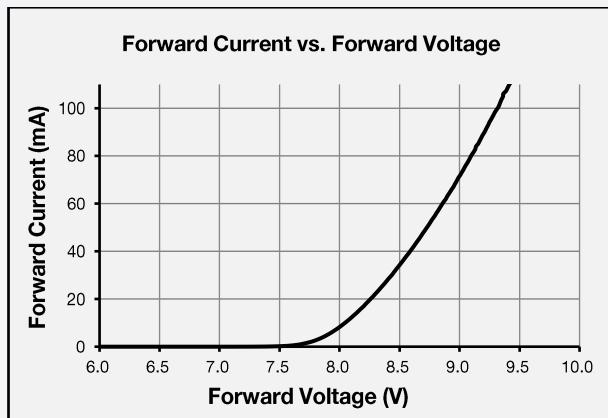




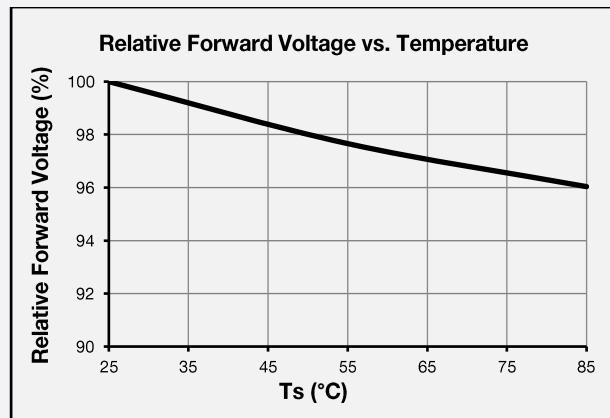
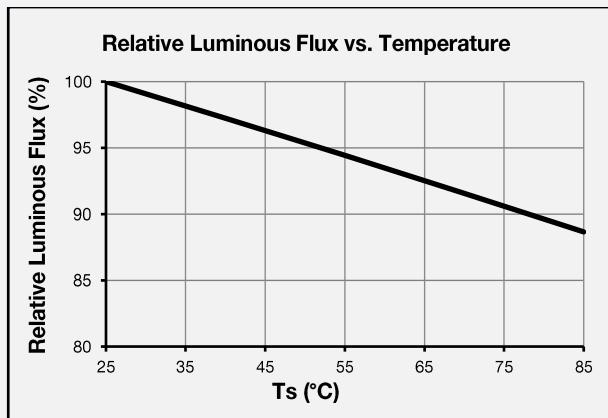
CCT: 6500 K (80 CRI)



b) Forward Current Characteristics ( $T_s = 25^\circ\text{C}$ )

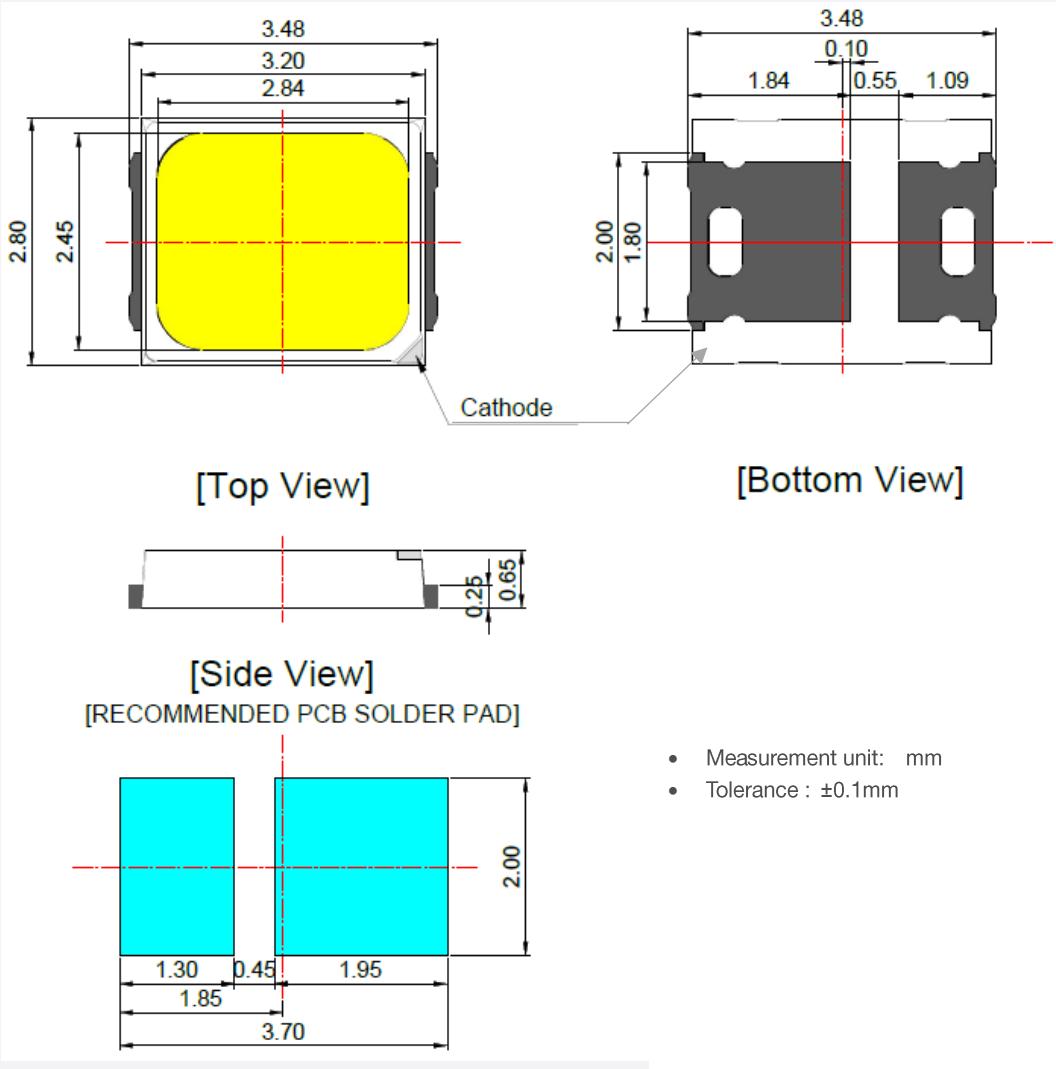


c) Temperature Characteristics ( $I_F = 100 \text{ mA}$ )





#### 4. Outline Drawing & Dimension



#### Notes:

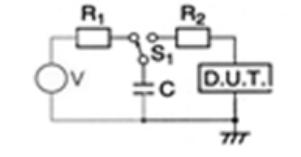
- 1)  $T_s$  point and measurement method:
  - ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach  $T_s$  point.
  - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

#### Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

## 5. Reliability Test Items & Conditions

### a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample No.
Room Temperature Life Test	25 °C, DC 110 mA	1000 h	22
High Temperature Life Test	85 °C, DC 110 mA	1000 h	22
High Temperature Humidity Life Test	60 °C, 90 % RH, DC 110 mA	1000 h	22
Low Temperature Life Test	-40 °C, DC 110 mA	1000 h	22
Powered Temperature Cycle Test	-45 °C ~ 85 °C, each 20 min, on/off 5 min Temp. Change time 100min, DC 110 mA	100 cycles	22
Temperature Cycling	-45 °C / 15 min ↔ 125 °C / 15 min	200 cycles	100
High Temperature Storage	120 °C	1000 h	11
Low Temperature Storage	-40 °C	1000 h	11
ESD (HBM)	 <p>R<sub>1</sub>: 10 MΩ  R<sub>2</sub>: 1.5 kΩ  C: 100 pF  V: ±2 kV</p>	5 times	30

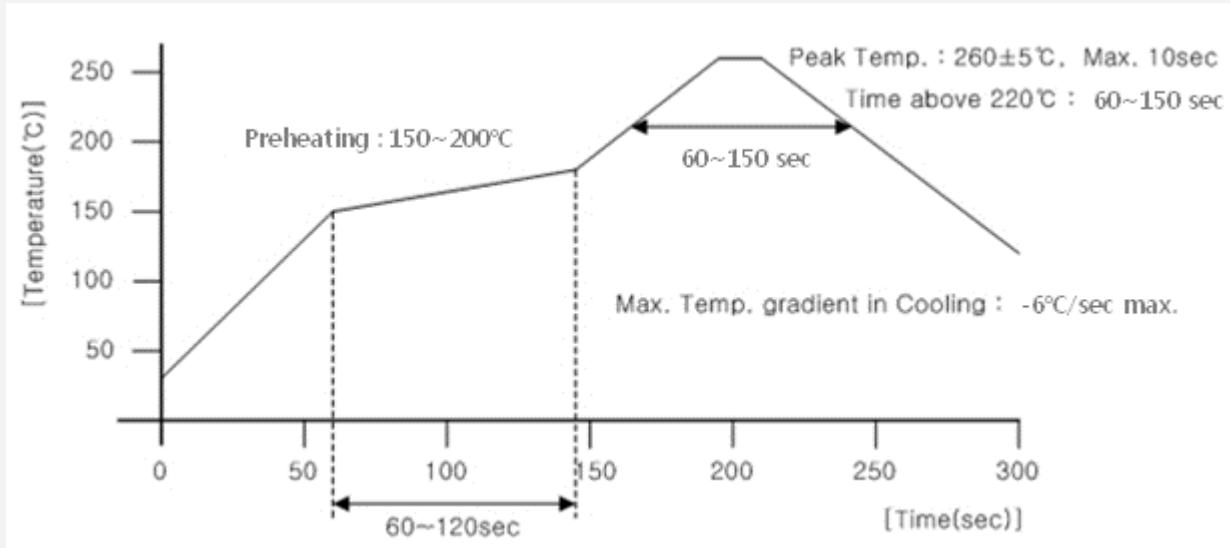
### b) Criteria for Judging the Damage

Item	Symbol	Test Condition (T <sub>s</sub> = 25 °C)	Limit	
			Min	Max
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 100 mA	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	Φ <sub>v</sub>	I <sub>F</sub> = 100 mA	Init. Value * 0.7	Init. Value * 1.1

## 6. Soldering Conditions

### a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.

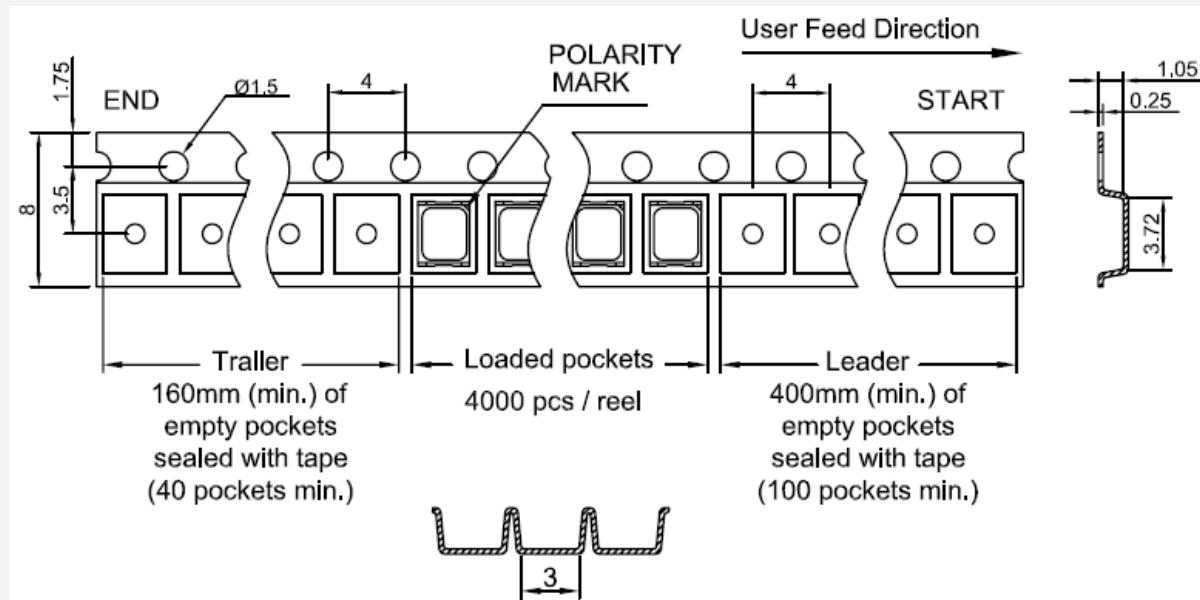


### b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.

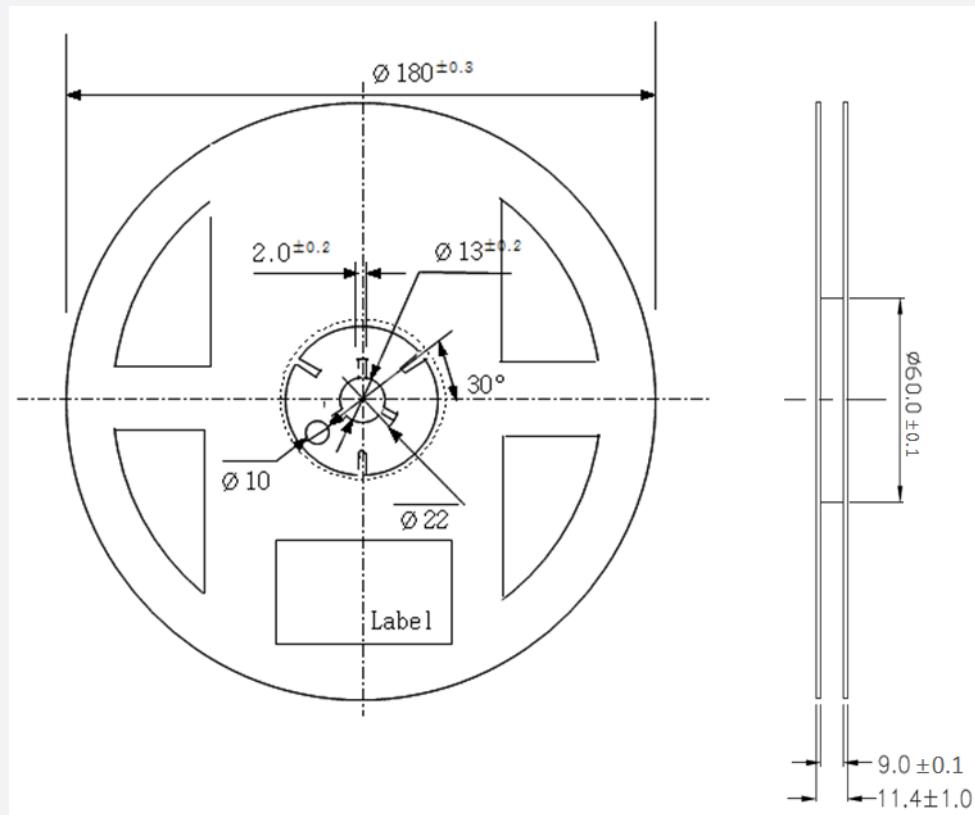
## 7. Tape & Reel

### a) Taping Dimension



**b) Reel Dimension (max 4,000 pcs)**

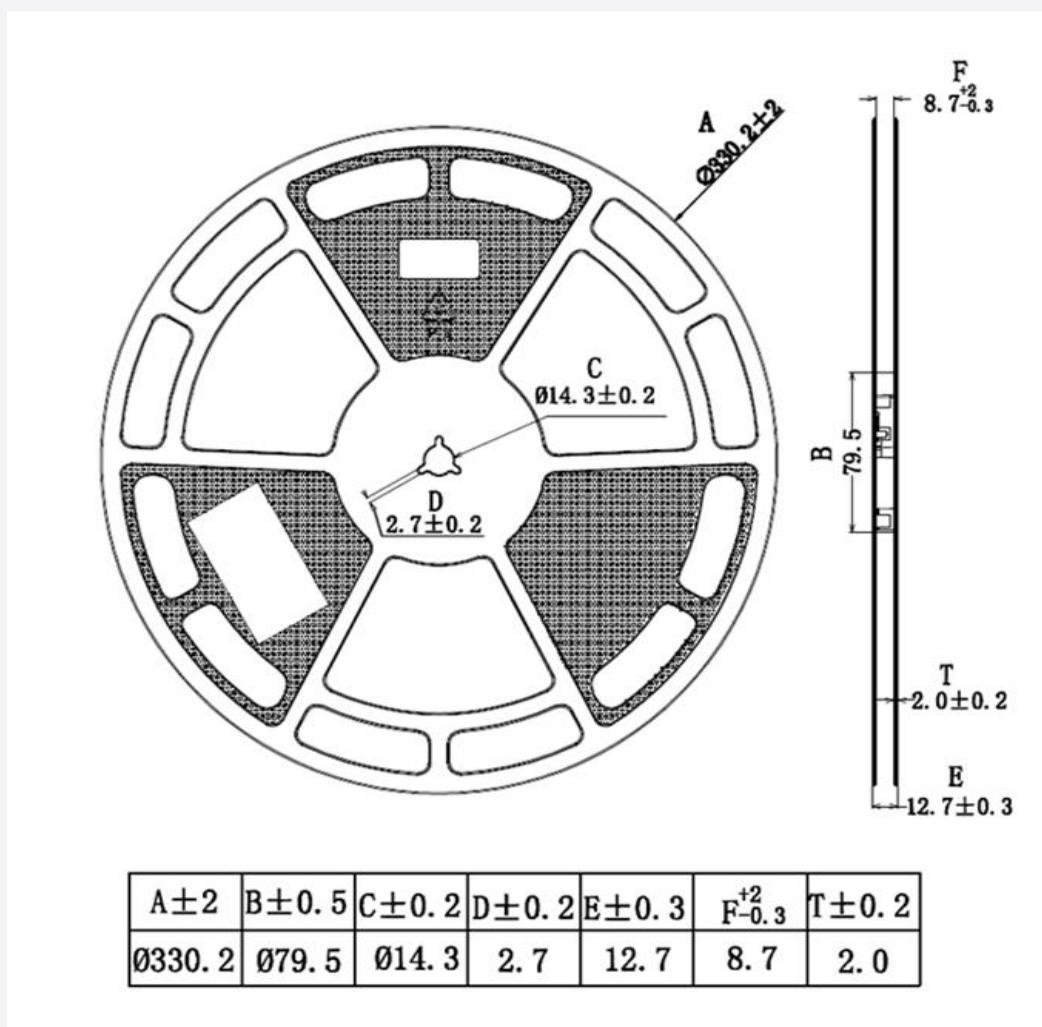
(unit: mm)

**Notes:**

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) All dimensions are millimeters (tolerance :  $\pm 0.2\text{mm}$ )
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

## c) Reel Dimension (max 16,000 pcs)

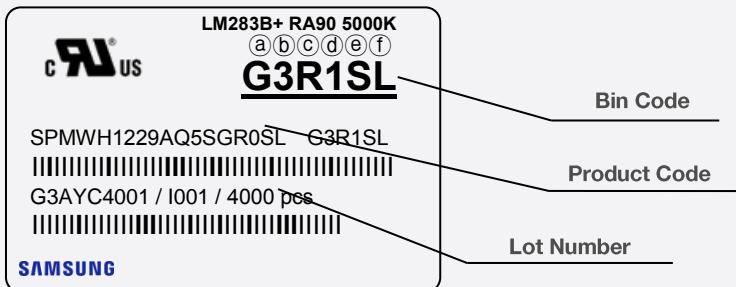
(unit: mm)

**Notes:**

- 1) Quantity: The quantity/reel is 16,000 pcs
- 2) All dimensions are millimeters (tolerance :  $\pm 0.2\text{mm}$ )
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

## 8. Label Structure

### a) Label Structure



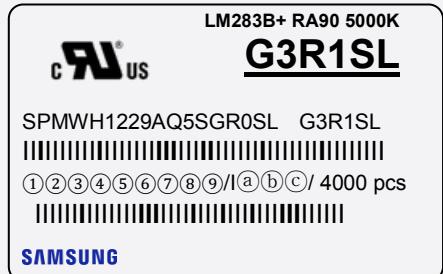
Note: Denoted bin code and product code above is only an example (see description on page 6)

Bin Code:

- ⓐⓑ: Forward Voltage bin (refer to page 10)
- ⓒⓓ: Chromaticity bin (refer to page 8-15)
- ⓔⓕ: Luminous Flux bin (refer to page 7)

### b) Lot Number

The lot number is composed of the following characters:



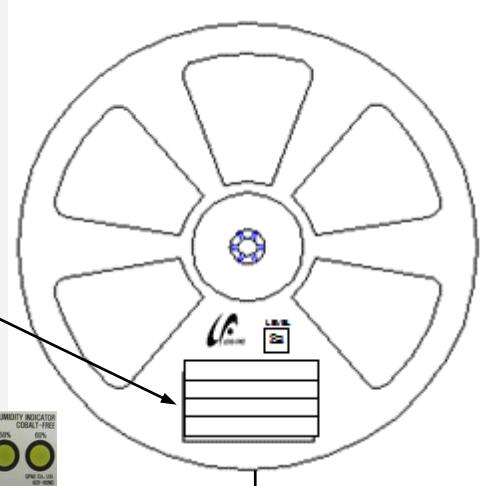
①②③④⑤⑥⑦⑧⑨ / ⓘⓐⓑⓒ / 4,000 pcs

- |         |   |
|---------|---|
| ①②      | : Production site (G3 or GP : Shenzhen, China)  |
| ②       | : 3 (LED)   |
| ③       | : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample) |
| ④       | : Year (Z: 2015, A: 2016, B: 2017...)   |
| ⑤       | : Month (1~9, A, B, C)  |
| ⑥       | : Day (1~9, A, B~V)   |
| ⑦⑧⑨ ⓐⓑⓒ | : Product serial number   |

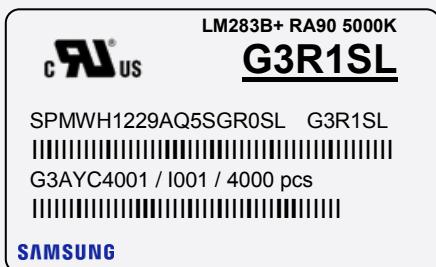
## 9. Packing Structure

### a) Packing Process

**Reel**



**Aluminum Vinyl Packing Bag**

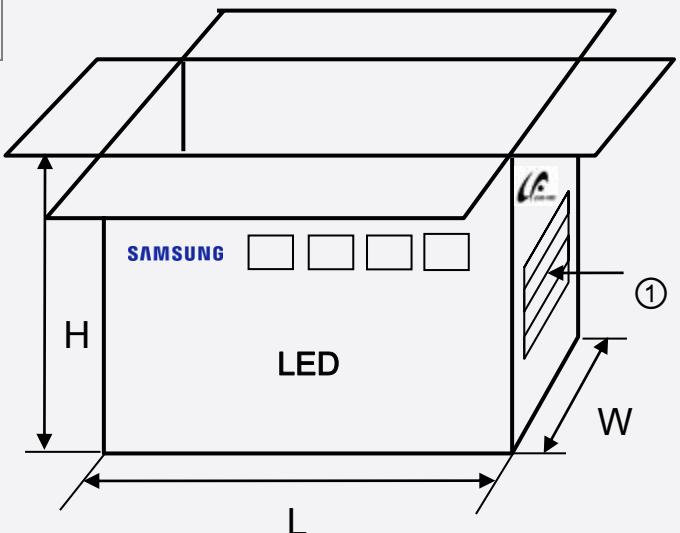
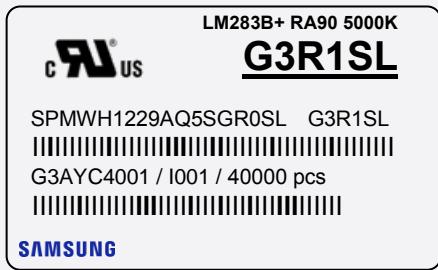


**Outer Box**

Material: Paper (SW3B(B))

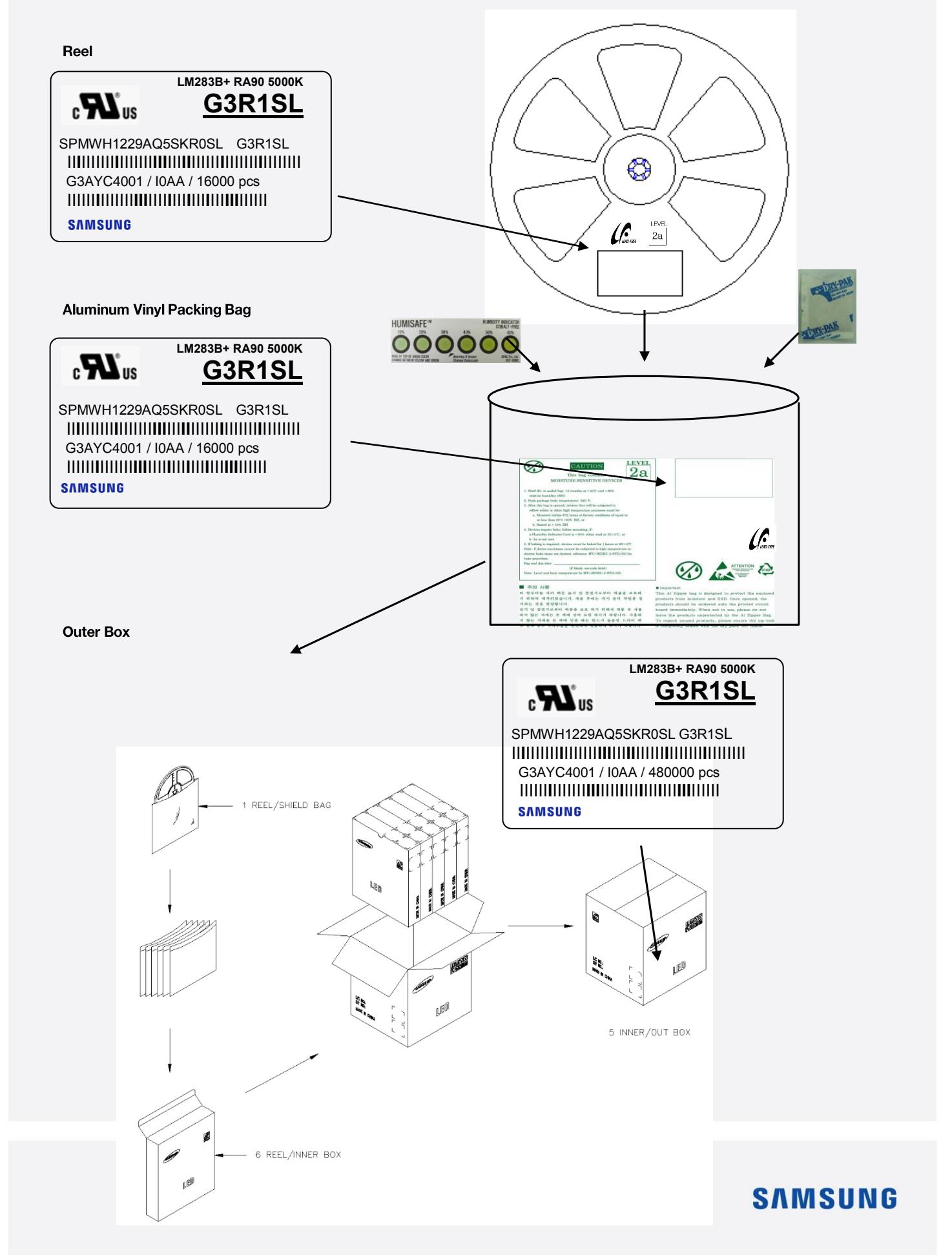
Type	Size (mm)			Note
	L	W	H	
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels
7 inch S	245 ± 5	220 ± 5	86 ± 5	Up to 5 reels

① Side Label



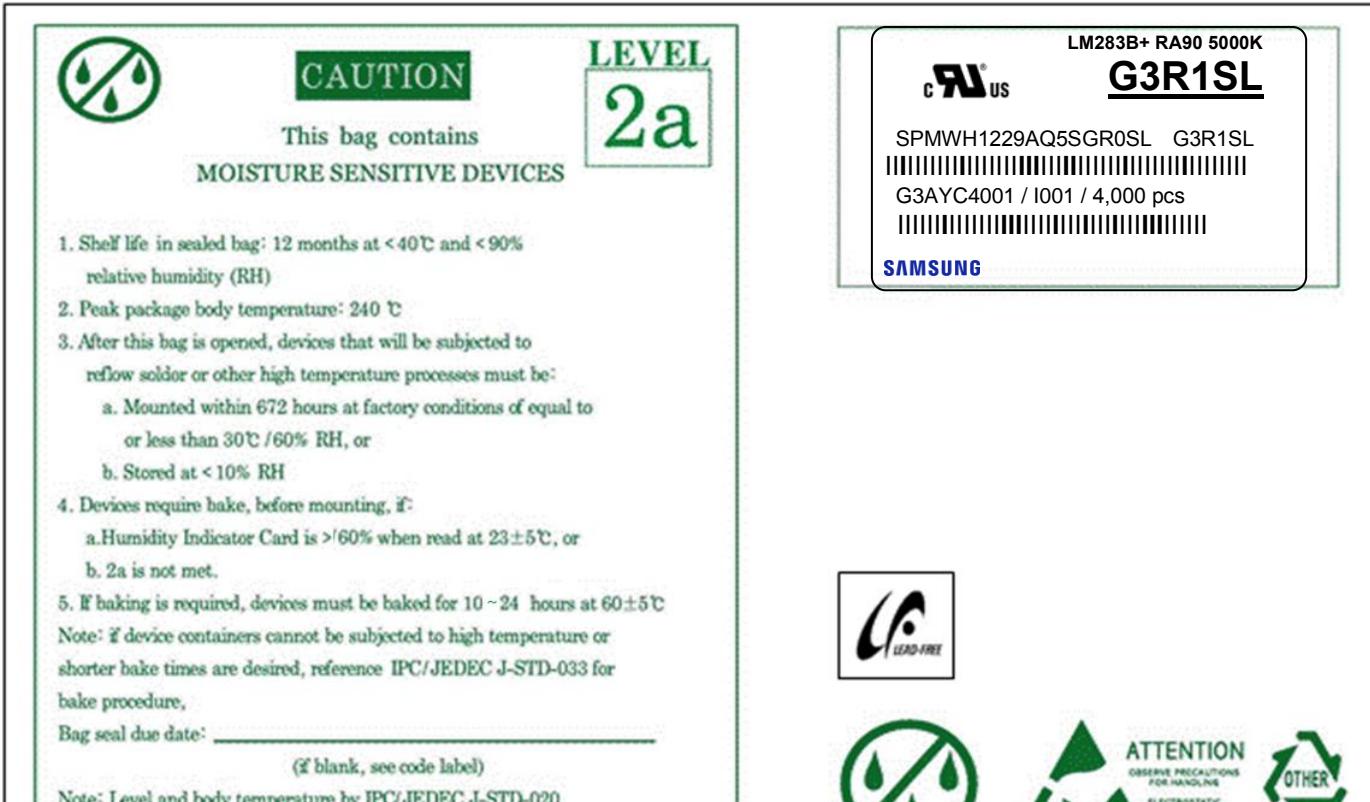
**SAMSUNG**

**b) Packing Process (The quantity of PKG on the Reel to be Max 16,000 pcs)**





### c) Aluminum Vinyl Packing Bag



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#### ■ Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products, please ensure the zip-lock is completely sealed with the dry pack left inside.

### d) Humidity Indicator Card inside Aluminum Vinyl Bag



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# Legal and additional information.

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